

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

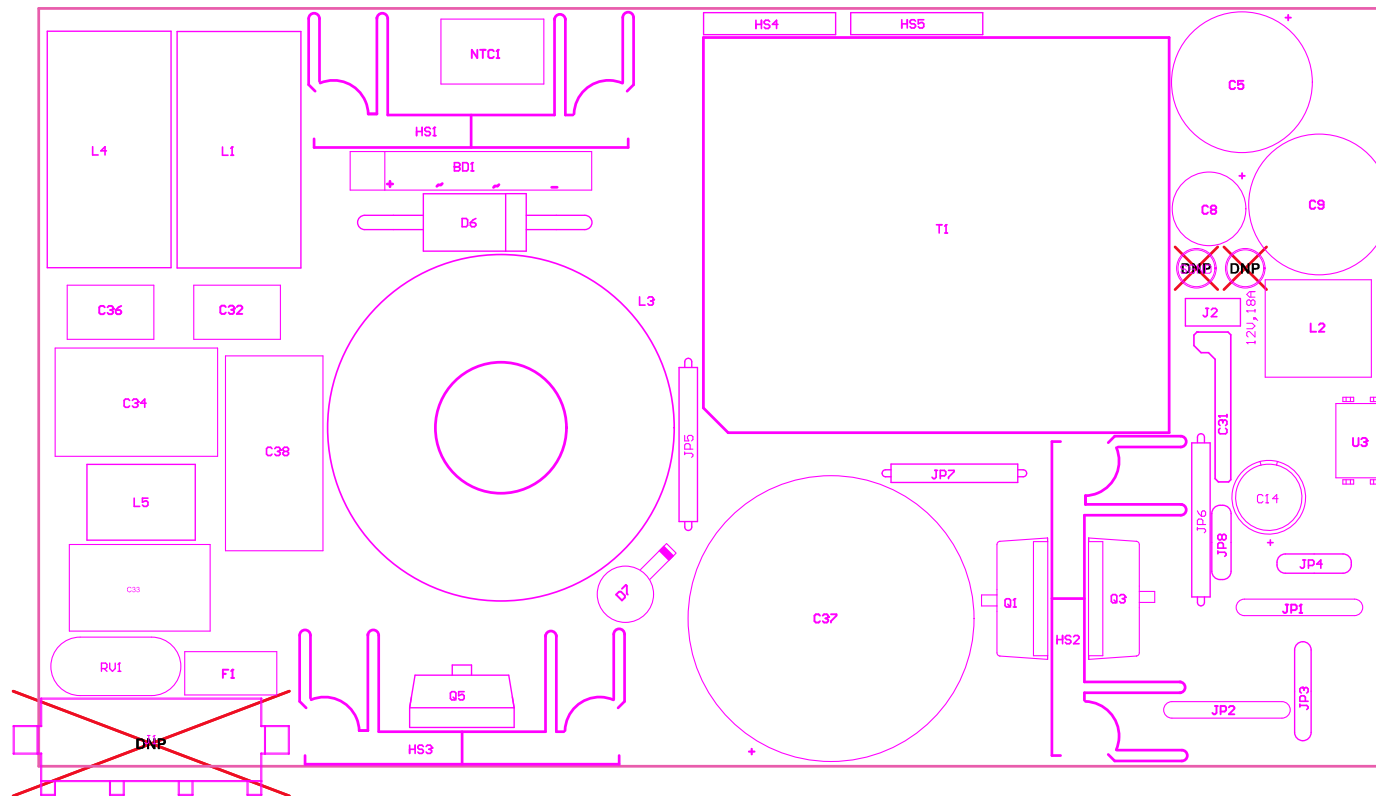
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

### 1. HS4 & HS5 Placement Instructions:

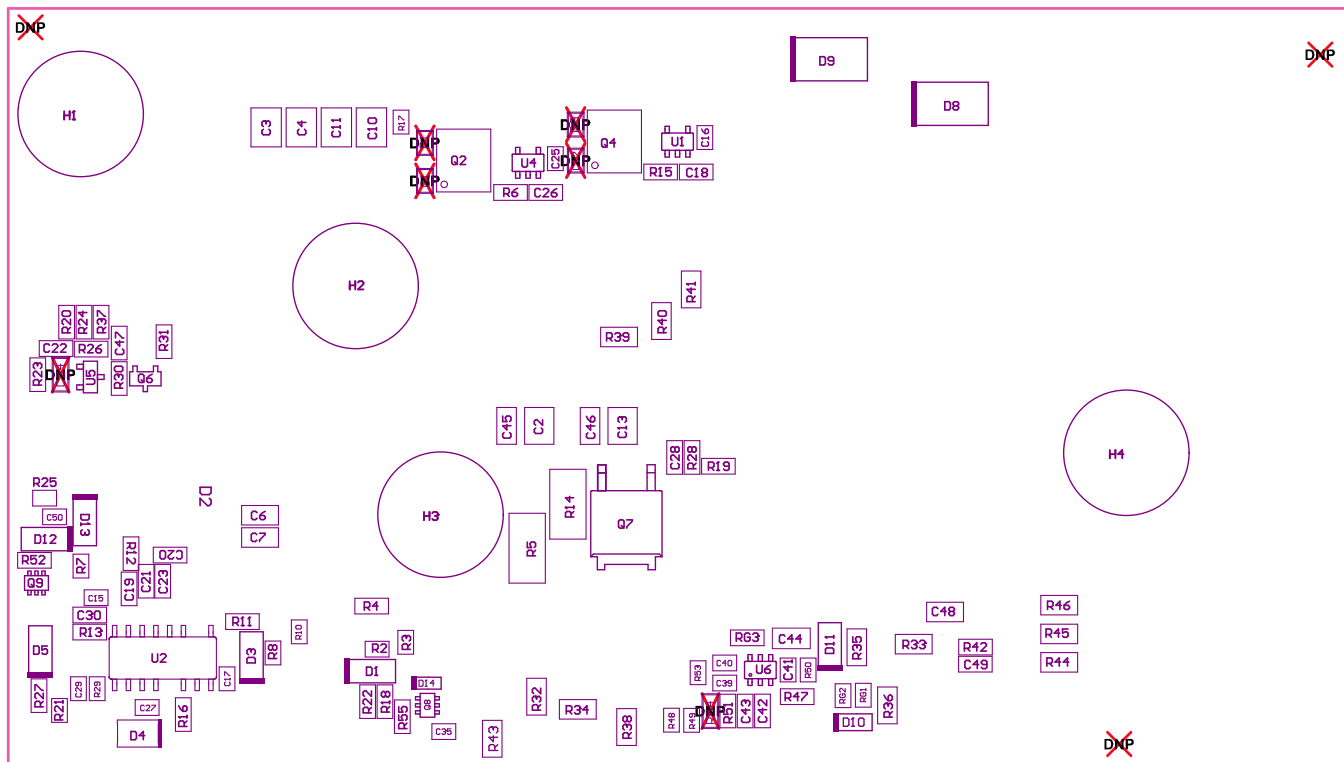
- a. Cut the Heat Sink into two equal vertical halves.
- b. Trim the Mounting lead to fit in the PCB Mounting Hole.

### 2. For all jumpers (JP1 to JP8) use thin insulated wire to mount across the nodes.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01557	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: TIDA-01557		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/15/2017 2:40:08 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01557	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: TIDA-01557		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/15/2017 2:40:09 PM	TEXAS INSTRUMENTS	

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